



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC050N04LS G		<b>Issued</b>		19. January 2018		
<b>MA#</b>		MA001254474						
<b>Package</b>		PG-TDSON-8-14		<b>Weight*</b>		101.31 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.426	1.41	1.41	14079	14079
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		96	
	non noble metal	zinc	7440-66-6	0.039	0.04		384	
	non noble metal	iron	7439-89-6	0.778	0.77		7680	
	non noble metal	copper	7440-50-8	31.590	31.18	32.00	311828	319988
wire	non noble metal	copper	7440-50-8	0.046	0.05	0.05	458	458
encapsulation	organic material	carbon black	1333-86-4	0.238	0.24		2351	
	plastics	epoxy resin	-	7.382	7.29		72869	
	inorganic material	silicondioxide	60676-86-0	40.006	39.47	47.00	394903	470123
leadfinish	non noble metal	tin	7440-31-5	1.243	1.23	1.23	12266	12266
plating	noble metal	silver	7440-22-4	0.037	0.04	0.04	369	369
solder	noble metal	silver	7440-22-4	0.040	0.04		392	
	non noble metal	tin	7440-31-5	0.032	0.03		314	
	non noble metal	lead	7439-92-1	1.518	1.50	1.57	14988	15694
heat sink CLIP	non noble metal	iron	7439-89-6	0.017	0.02		167	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		50	
	non noble metal	copper	7440-50-8	16.898	16.68	16.70	166806	167023
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com